

PATENT APPLICATION
Docket No. 9903-070
Client No. S02US037

Applicant: Hee-Jin Park, Tae-Jin Park and Eun-Chul Ahn
Serial No. not yet assigned Examiner: not yet assigned
Filing Date: November 20, 2003 Art Unit: not yet assigned
Title: STACKED CHIP PACKAGE WITH HEAT TRANSFER WIRES

INFORMATION DISCLOSURE CITATION
FORM PTO-1449 (Modified)

U.S. PATENT DOCUMENTS

Exam <u>Init</u>	Ref	Document <u>Number</u>	Issue <u>Date</u>	Name	Class	Sub <u>Class</u>
<u>TJ</u>	_____	US 6,294,838 B1	9/25/2001	Peng		

FOREIGN PATENT DOCUMENTS

Exam <u>Init</u>	Ref	Document <u>Number</u>	Publication <u>Date</u>	Country	Name
<u>TJ</u>	_____	2002-43395	6/10/2002	Korea	Eun-Yeong Jung
<u>TJ</u>	_____	2002-36191	5/16/2002	Korea	Beak, et al.

OTHER DOCUMENTS

Exam <u>Init</u>	Ref	Author, Title, Date, Pertinent Pages, Etc.)
<u>TJ</u>	_____	English language of Korean Abstract for Korean Patent Publication No. 2002-43395 published 6/10/2002.
<u>TJ</u>	_____	English language of Korean Abstract for Korean Patent Publication No. 2002-36191, published 5/16/2002.

Examiner: Thompson

Date Considered: 10/27/04